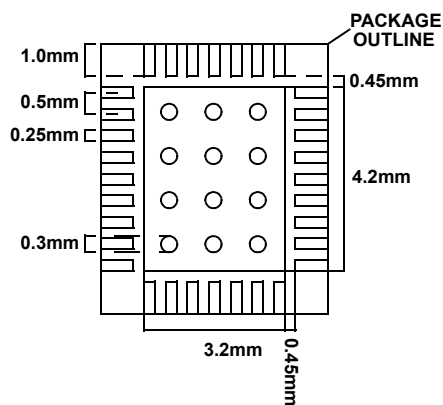
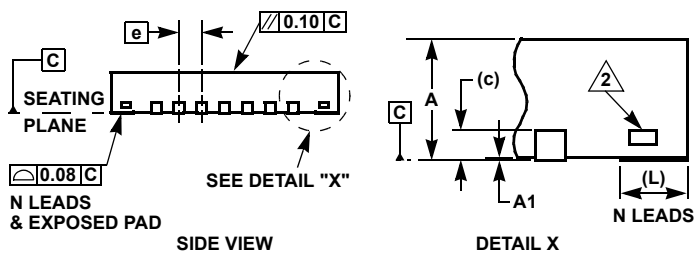
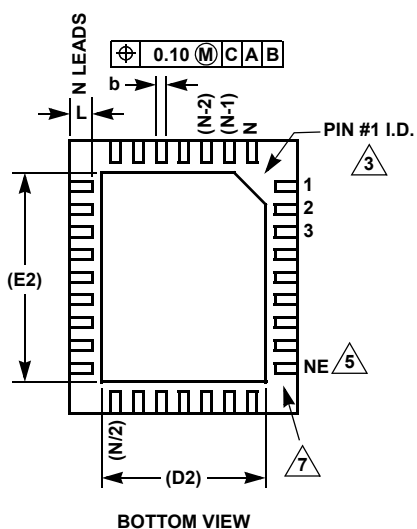
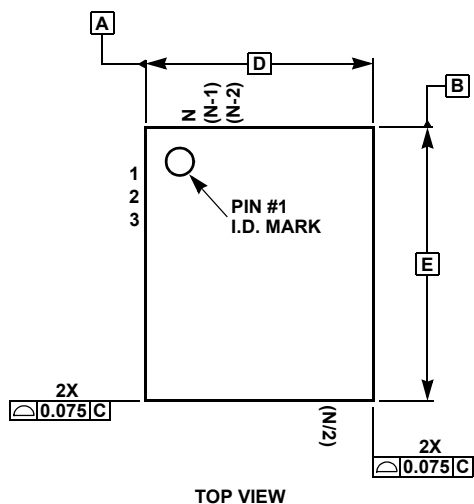


# Plastic Packages for Integrated Circuits

## Quad Flat No-Lead Plastic Package (QFN) Micro Lead Frame Plastic Package (MLFP)

**L32.5x6C** (One of 10 Packages in MDP0046)  
32 LEAD QUAD FLAT NO-LEAD PLASTIC PACKAGE  
(COMPLIANT TO JEDEC MO-220)



SYMBOL	MILLIMETERS			NOTES
	MIN	NOMINAL	MAX	
A	0.80	0.90	1.00	-
A1	0.00	0.02	0.05	-
D	5.00 BSC			-
D2	3.50 REF			-
E	6.00 BSC			-
E2	4.50 REF			-
L	0.35	0.40	0.45	-
b	0.23	0.25	0.27	-
c	0.20 REF			-
e	0.50 BSC			-
N	32 REF			4
ND	7 REF			6
NE	9 REF			5

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### NOTES:

1. Dimensioning and tolerancing per ASME Y14.5M-1994.
2. Tiebar view shown is a non-functional feature.
3. Bottom-side pin #1 I.D. is a diepad chamfer as shown.
4. N is the total number of terminals on the device.
5. NE is the number of terminals on the "E" side of the package (or Y-direction).
6. ND is the number of terminals on the "D" side of the package (or X-direction).  $ND = (N/2) - NE$ .
7. Inward end of terminal may be square or circular in shape with radius  $(b/2)$  as shown.